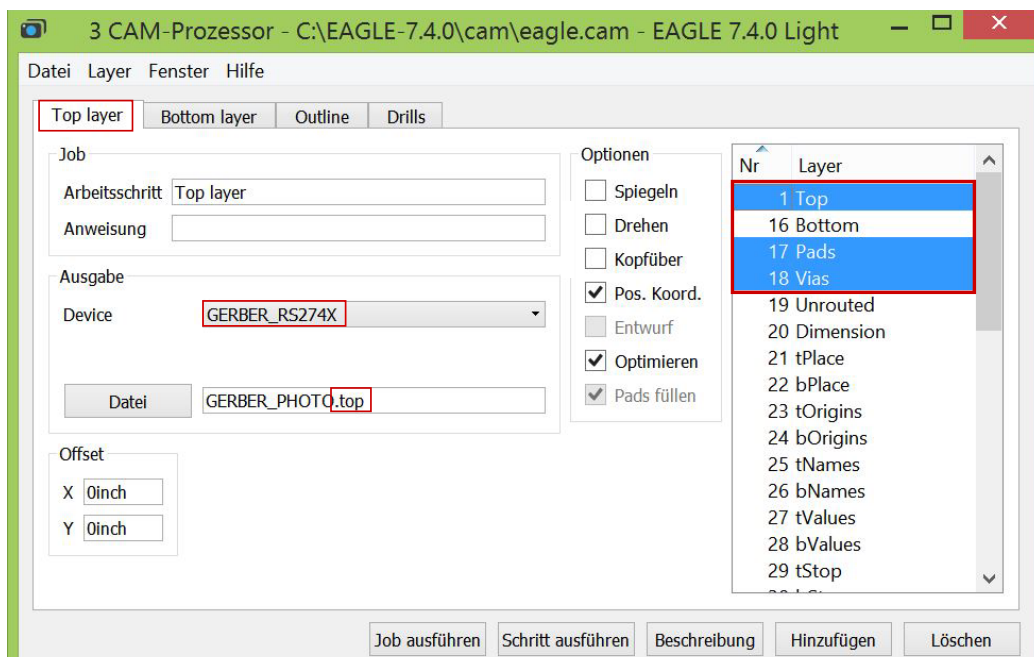
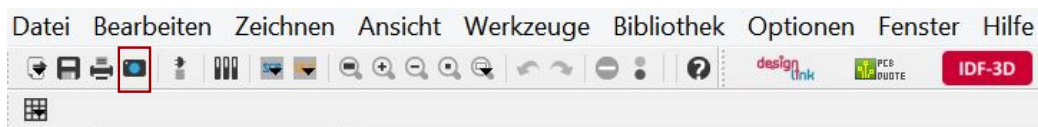


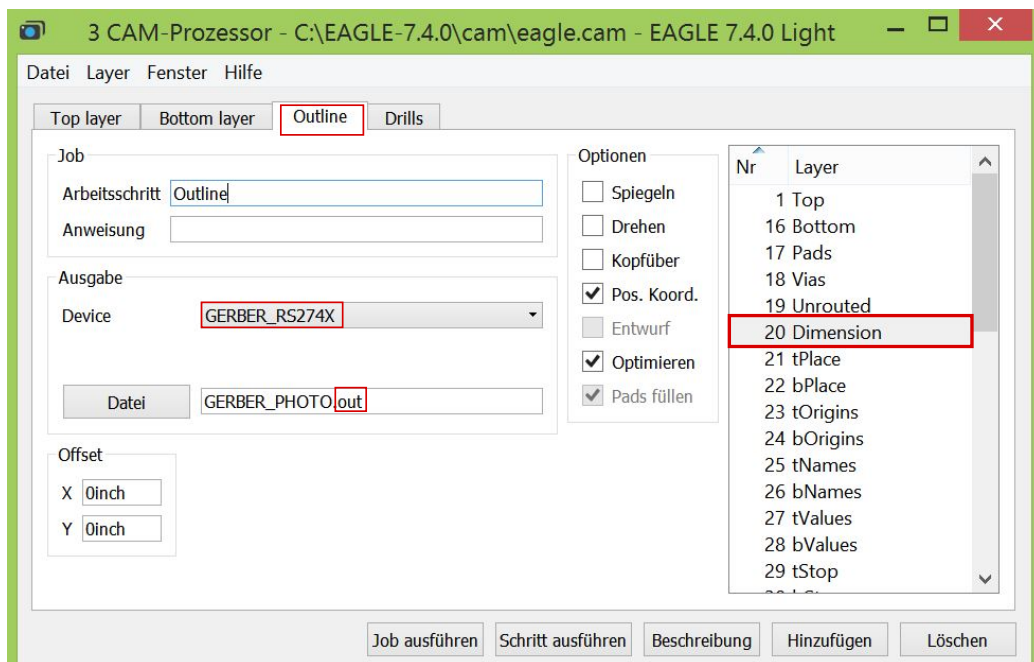
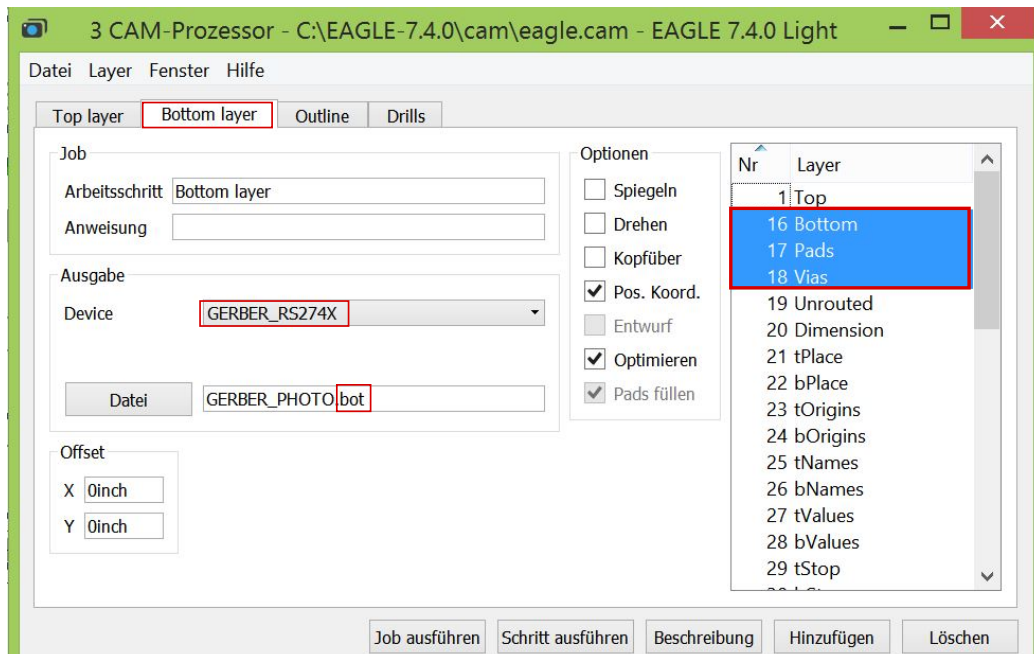
Step by Step Instruction

From Eagle file to Finished Board


Export Eagle Files

You need four files which you can export in *Eagle* with the *Datei* → *CAM Prozessor*. The relevant settings are shown in the figures below.






Prozessplanungsassistent



CircuitPro



Überblick

Prozessart

Anzahl Layer


Substrat

Durchkontaktierung

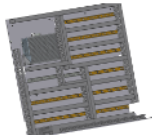
Oberflächenbehandlung

Zusammenfassung

Wählen Sie die Art des Prozesses aus.



☒ Leiterplatten bearbeiten




☐ 2,5D-Elemente bearbeit...


Weiter

Abbrechen

Prozessplanungsassistent



CircuitPro



Überblick

Prozessart

Anzahl Layer


Substrat

Durchkontaktierung


Oberflächenbehandlung

Zusammenfassung


Wie viele Layer wird die Leiterplatte haben?



☒ Einseitig Bottom



☐ Einseitig Top



☐ Doppelseitig

Zurück

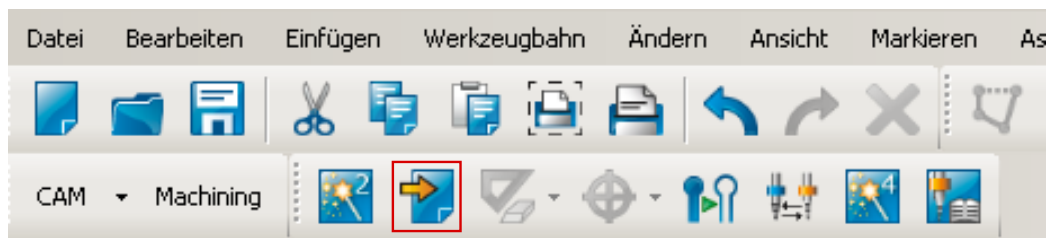
Weiter

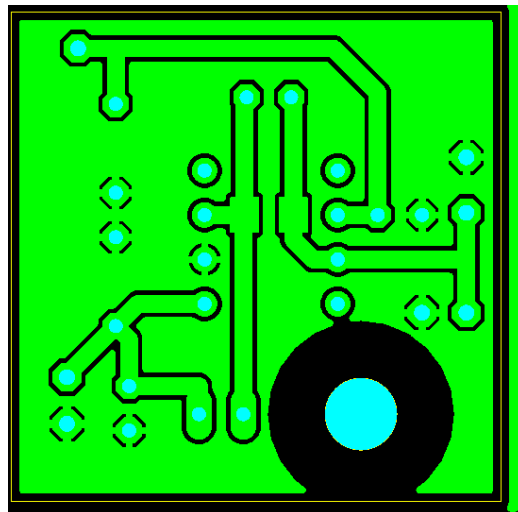
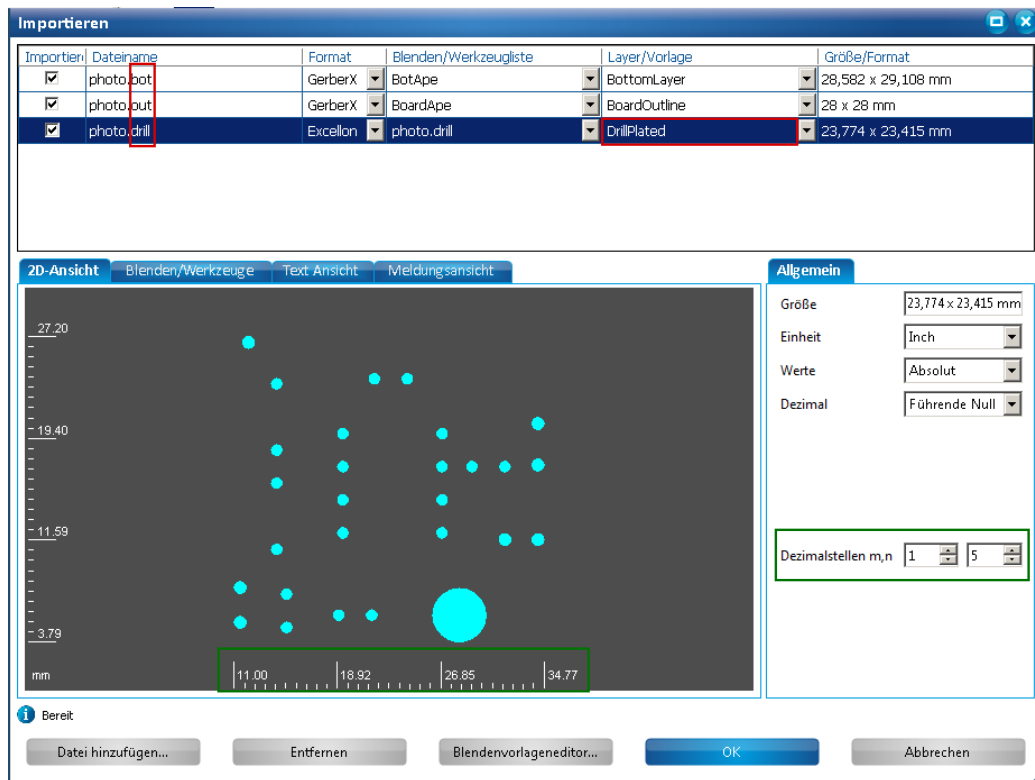
Abbrechen

4



Step 2: Datei aus Fremdformat importieren

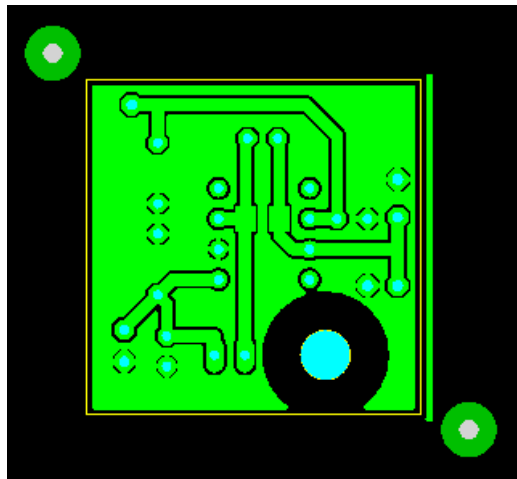
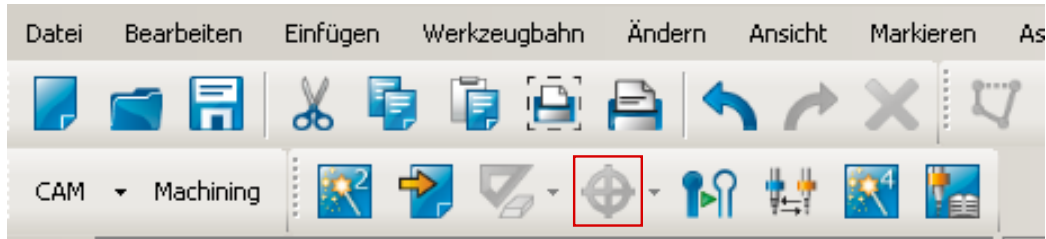




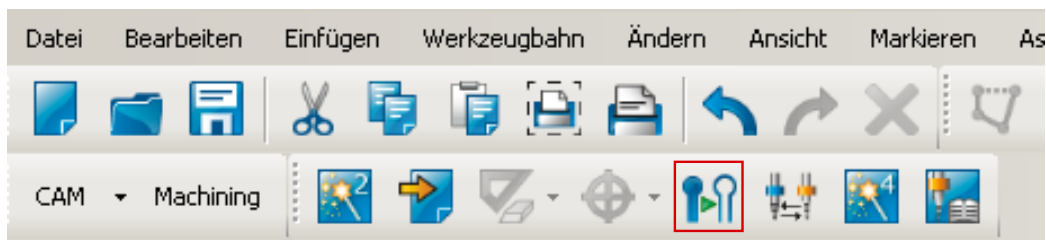
Now import the previous exported .top, .bot, .out and . drill files. Usually the .top, .bot, .out files are directly identified. However the .dril file is not, so that you have to choose *DrillPlated* in the *Layer/Vorlage* section. Sometimes the magnitude of the dimension is not correct. Therefore check the magnitude of your board and change the *Dezimalstellen* which is marked in green.

Step 3: Passermarken setzen

The *Passermarken* are orientation points for the double sided boards. Choose *Passermarken setzen* → *Fiduita* and place marks beside the left lower and right upper corner of the board.



Step 4: Fräsbahngenerator




Here are a lot of settings possible. The below shown settings are recommended.

Fräsbahngenerator

Globale Prozesseinstellungen

Materialtyp: FR4 Kupferschichtstärke: 18 µm ☐ HF-Anwendung

Isolation


 1/4

☒ Ausführen
Details anzeigen

Isolationsmethode: Einfach

Beschreibung: Isolierung mit einfachem Isolationskanal
Kürzeste Bearbeitungszeit

Konturfraßen

 5/6

☒ Ausführen
Details anzeigen

Konturfräsmethode: Eckstege


Beschreibung: Konturfraßen mit Stegen in jeder Ecke

Fräsbahngenerator

Globale Prozesseinstellungen

Materialtyp: FR4 Kupferschichtstärke: 18 µm ☐ HF-Anwendung

Isolation

 2/4

☒ Ausführen
Details ausblenden

Isolationsmethode: Einfach, Pads doppelt

Beschreibung: Isolierung mit einfachem Isolationskanal
Doppelter Isolationskanal für Pads.
Kurze Bearbeitungszeit

Quelle: <Wiring> layers Isolationsbreite: 0,5 mm

Primär: Universal Cutter 0,2 mm Pad-Isolation: 0,25 mm 2 Fräskanäle

Verfügbare Werkzeuge:

- ☒ Micro Cutter 0,1 mm
- ☒ Universal Cutter 0,2 mm
- ☐ End Mill (RF) 0,25 mm
- ☐ End Mill (RF) 0,4 mm
- ☐ End Mill 1 mm
- ☐ D104 Laser Default
- ☐ D104 Laser
- ☐ End Mill (RF) 0,15 mm

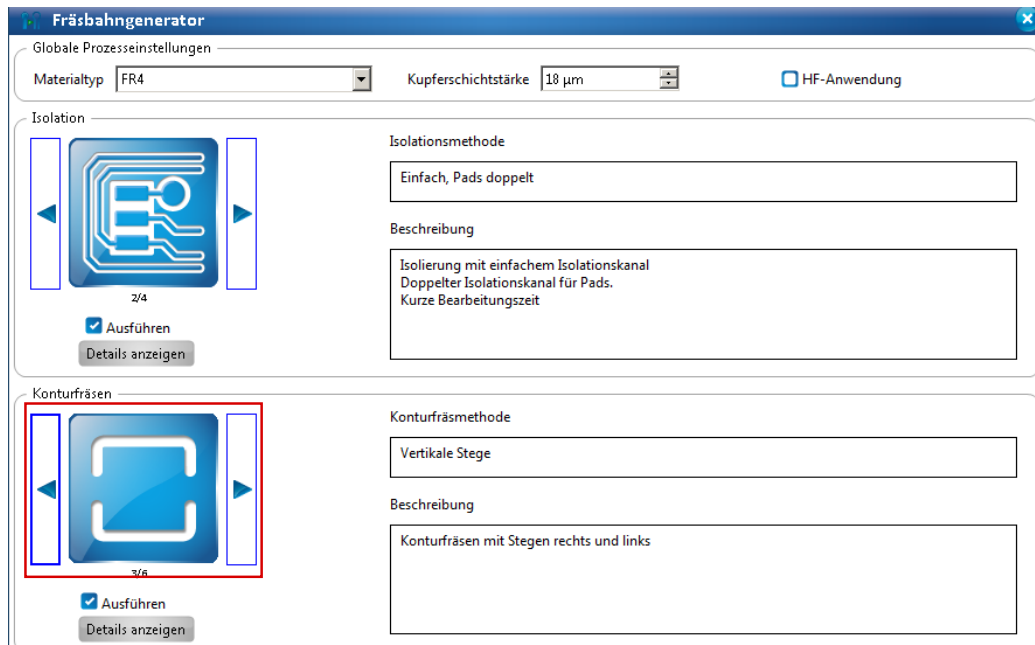
Rubout: <Kein Rubout> Konzentrisch

Toleranz: 0,002 mm

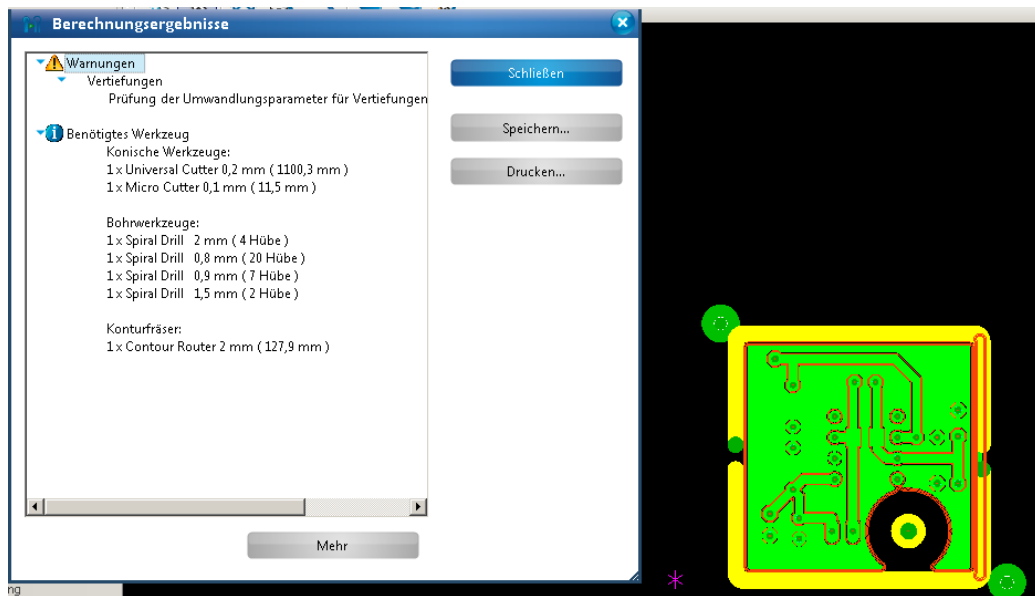
☐ Optimierte Rubout-Fläche erzeugen ☒ Existierende Werkzeugbahn ersetzen

☒ Isolation erzwingen ☒ Entferne Spitzen

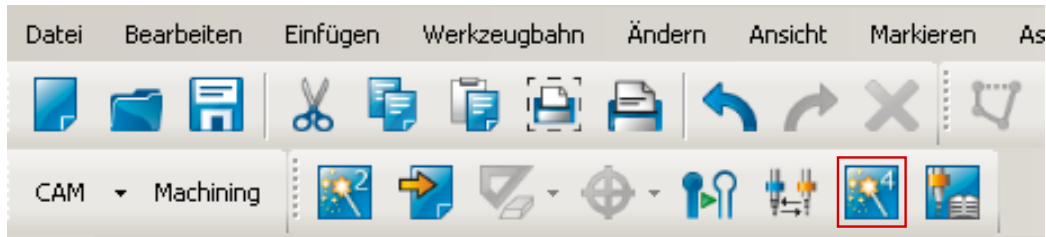
☒ Innere Isolation ausführen ☐ Designregelprüfung



Now you find a list of the needed and used tools. It can happen that you seem to need a tool which is not available. E.g. for holes with a diameter of 0.6 mm. If the size of the hole is not needed to be 0.6 mm but can also be 0.7 mm then choose manually the best tool to replace it with. If there is an error which seems to be important ask someone.



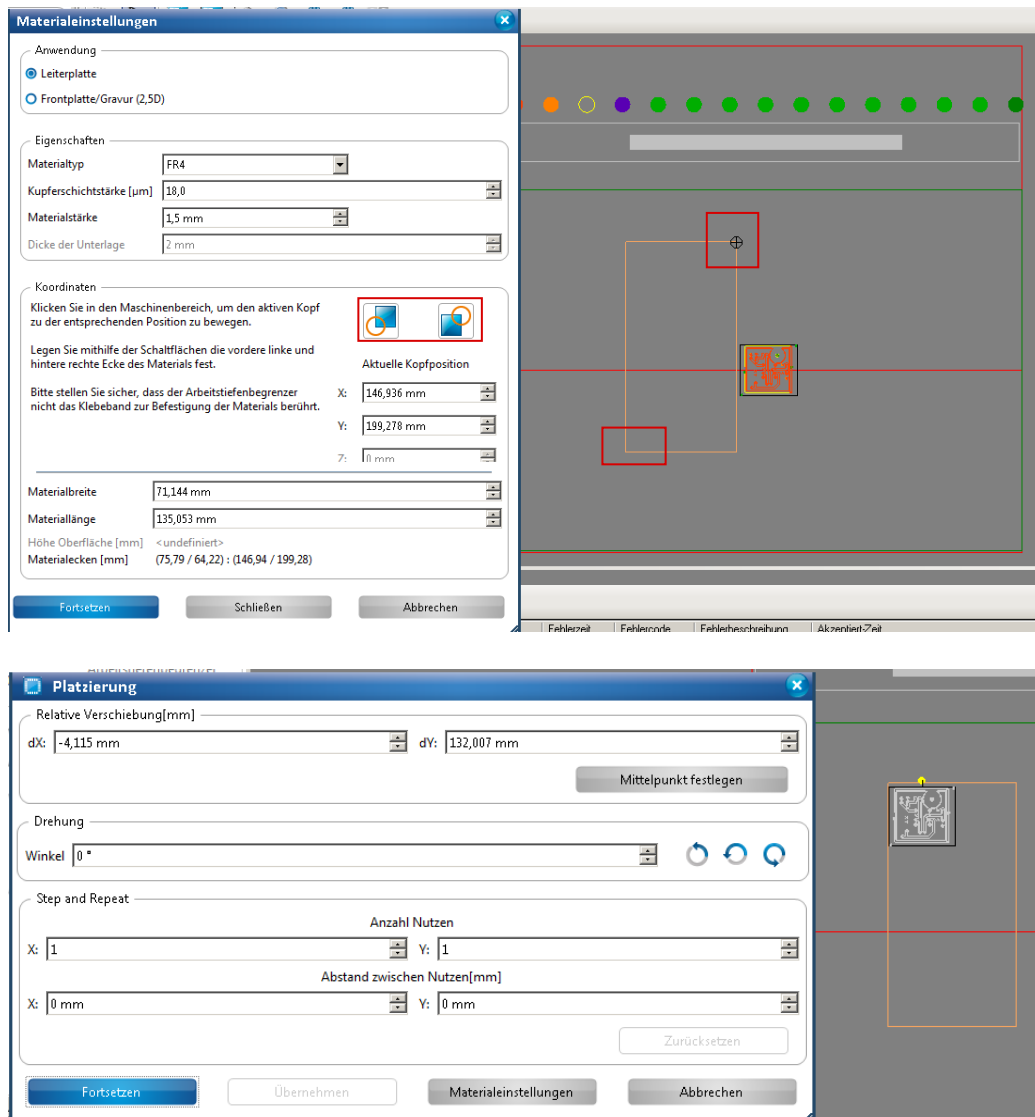
Step 5: Produktionsassistenten starten



Mount the board material with the provided tape.



Now move the milling head by clicking with your mouse on the grey screen to set the limits of the material. You set the limits by defining the lower left and upper right corner as before for the *Passermarken*. Afterwards mark the board and place it in the area. If you have a double sided board you have to turn the material upside down manually. Therefore follow the given instructions.



Step 5: Check the Result

An often occurred problem was that not all pads for SMD parts were separated properly. You might want to check especially small areas carefully before soldering.